

X10846

Components and Spares



# HEATSINK COMPOUND SYRINGE

TM 500 Thermal Grease Paste CPU

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## KEY FEATURES:

- ✓ **Composition:** It contains 5% silicone compounds, 65% carbon compounds, and 30% metal oxide compounds.
- ✓ **Thermal Properties:** Offers excellent thermal conductivity (>1.93 W/m-K) and low thermal impedance (<0.073 °C\*in<sup>2</sup>/W).
- ✓ **Physical Characteristics:** The grease is grey in colour, has a specific gravity of 2.5, and operates effectively within a temperature range of -30°C to 300°C.
- ✓ **Stability:** It demonstrates minimal evaporation (0.001%) and bleed (0.05%) at 150°C over 24 hours, ensuring long-term reliability.
- ✓ **Electrical Insulation:** With a dielectric constant of 5.1 at 100Hz, it provides good electrical insulation.

A heatsink compound syringe is a handy tool for applying thermal paste to electronic components that need efficient cooling. Thermal paste is a substance that fills the gaps between the heatsink and the component, improving heat transfer and preventing overheating. A syringe allows you to apply the right amount of paste with precision and ease. Here are some features and benefits of using a heatsink compound syringe:

- It contains high-quality thermal paste that has high thermal conductivity, low metallic impurity content, and excellent moisture buffer.
- It has a needle tip that lets you control the flow and direction of the paste, avoiding spills and waste.
- It is compatible with most types of heatsinks and electronic components.
- It is easy to use and store, requiring no special tools or skills.

## TECHNICAL SPECIFICATIONS

Items	Units	Environment	Test method	Test result
Colour	No	25°C	Visual	<b>Grey</b>
Thermal Conductivity	W/m-K	No	ROCT8.140-82	<b>&gt;1.93</b>
Thermal Impedance	°C-in <sup>2</sup> /W	No	ROCT8.140-82	<b>&lt;0.073</b>
Specific Gravity	No	25°C	ASTM D1475	<b>2.5</b>
Evaporation	%	150°C/24Hours	Fed.Std.791	<b>0.001</b>
Bleed	%	150°C/24Hours	Fed.Std.791	<b>0.05</b>
Dielectric Constant	No	100Hz	ASTM D150	<b>5.1</b>
Viscosity	No	25°C	---	<b>NON</b>
Thixotropic Index	1/10 mm	25°C	GB/T-269	<b>380±10</b>
Moment Beared Temperature	°C	No	No	<b>-50~340°C</b>
Operation Temperature	°C	No	No	<b>-30~300°C</b>
<b>Compounds</b>				
Silicone Compounds			<b>5%</b>	
Carbon Compounds			<b>65%</b>	
Metal Oxide Compounds			<b>30%</b>	
✘ The product temperature, not spontaneous combustion, mining the general methods can be stored at room temperature				

## APPLICATIONS:

TM500 is essential for heat management in various tech devices:

- **PCs & Laptops:** Cooling CPUs/GPUs.
- **LEDs:** Managing heat.
- **Electronics:** Securing power components.
- **Machines:** Industrial heat control.



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# HEATSINK COMPOUND SYRINGE

TM 500 Thermal Grease Paste CPU

## PRODUCT CODE AND RELATED PRODUCT CODE

Product Code	Product Description
Z01062	1g Heatsink compound syringe



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